

# Zhaolong

## List of Publications by Year in descending order

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Version: 2024-02-01

21  
papers

589  
citations

566801

15  
h-index

752256

20  
g-index

21  
all docs

21  
docs citations

21  
times ranked

419  
citing authors

#	ARTICLE	IF	CITATIONS
1	Design of novel low-density refractory high entropy alloys for high-temperature applications. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2019, 755, 318-322.	2.6	73
2	Microstructures and mechanical properties of HfNbTaTiZrW and HfNbTaTiZrMoW refractory high-entropy alloys. <i>Journal of Alloys and Compounds</i> , 2019, 803, 778-785.	2.8	69
3	Effects of cobalt on the nucleation and grain refinement of Sn-3Ag-0.5Cu solders. <i>Journal of Alloys and Compounds</i> , 2016, 682, 326-337.	2.8	66
4	Nucleation of tin on the Cu <sub>6</sub> Sn <sub>5</sub> layer in electronic interconnections. <i>Acta Materialia</i> , 2017, 123, 404-415.	3.8	56
5	Harnessing heterogeneous nucleation to control tin orientations in electronic interconnections. <i>Nature Communications</i> , 2017, 8, 1916.	5.8	50
6	Nucleation, grain orientations, and microstructure of Sn-3Ag-0.5Cu soldered on cobalt substrates. <i>Journal of Alloys and Compounds</i> , 2017, 706, 596-608.	2.8	36
7	Nucleation and twinning in tin droplet solidification on single crystal intermetallic compounds. <i>Acta Materialia</i> , 2018, 150, 281-294.	3.8	36
8	Grain refinement of electronic solders: The potential of combining solute with nucleant particles. <i>Journal of Alloys and Compounds</i> , 2017, 715, 471-485.	2.8	33
9	Sn addition on the tensile properties of high temperature Zn-4Al-3Mg solder alloys. <i>Microelectronics Reliability</i> , 2012, 52, 579-584.	0.9	22
10	Microstructural and mechanical properties of in-situ micro-laminated TiC/Ti composite synthesised. <i>Materials Letters</i> , 2018, 228, 1-4.	1.3	21
11	Microstructures and mechanical properties of CoCrFeNiHf <sub>x</sub> high-entropy alloys. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2020, 792, 139820.	2.6	21
12	Effects of Si additions on microstructures and mechanical properties of VNbTiTaSi refractory high-entropy alloys. <i>Journal of Alloys and Compounds</i> , 2022, 900, 163517.	2.8	19
13	Static and dynamic mechanical properties of Yttrium Aluminum Garnet (YAG). <i>Ceramics International</i> , 2019, 45, 12256-12263.	2.3	18
14	Mechanisms of beta-Sn nucleation and microstructure evolution in Sn-Ag-Cu solders containing titanium. <i>Journal of Alloys and Compounds</i> , 2019, 777, 1357-1366.	2.8	18
15	Influence of tantalum on mechanical, ferroelectric and dielectric properties of Bi-excess Bi <sub>3.25</sub> La <sub>0.75</sub> Ti <sub>3</sub> O <sub>12</sub> thin film. <i>Applied Surface Science</i> , 2019, 463, 1141-1147.	3.1	17
16	Effects of Ti foil thickness on microstructures and mechanical properties of in situ synthesized micro-laminated TiC/Ti composites. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2019, 767, 138296.	2.6	11
17	Controlling <sup>117</sup> Sn grain orientations in electronic interconnects with single-crystal Cobalt substrates. <i>Acta Materialia</i> , 2020, 194, 422-436.	3.8	9
18	Characterization of highly (117)-oriented Bi <sub>3.25</sub> La <sub>0.75</sub> Ti <sub>3</sub> O <sub>12</sub> thin films prepared by rf-magnetron sputtering technique. <i>Solid State Communications</i> , 2018, 278, 31-35.	0.9	6

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19	Effect of thickness and crystalline morphology on electrical properties of rf-magnetron sputtering deposited Bi <sub>4</sub> Ti <sub>3</sub> O <sub>12</sub> thin films. <i>Ceramics International</i> , 2018, 44, 20465-20471.	2.3	5
20	Crystallization evolution and ferroelectric behavior of Bi <sub>3.25</sub> La <sub>0.75</sub> Ti <sub>3</sub> O <sub>12</sub> -based thin films prepared by rf-magnetron sputtering. <i>Journal of Materials Science: Materials in Electronics</i> , 2019, 30, 8974-8979.	1.1	2
21	Solidification of Sn-3Ag-0.5Cu and Sn-0.7Cu-0.05Ni Solders. <i>Materials Science Forum</i> , 0, 857, 44-48.	0.3	1